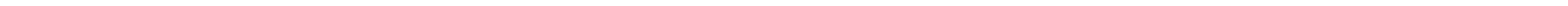




Nano(n)-machining, surface analysis and characterization measurements of a copper photocathode at SPARC_LAB

Jessica Scifo

On behalf of SPARC_LAB collaboration



- Motivation
- Machining and results before and after machining
- Fourier transform of AFM images and surface roughness induced emittance
- Total beam emittance measurements
- Preliminary study of Yttrium photocathodes
- Conclusions

Motivation

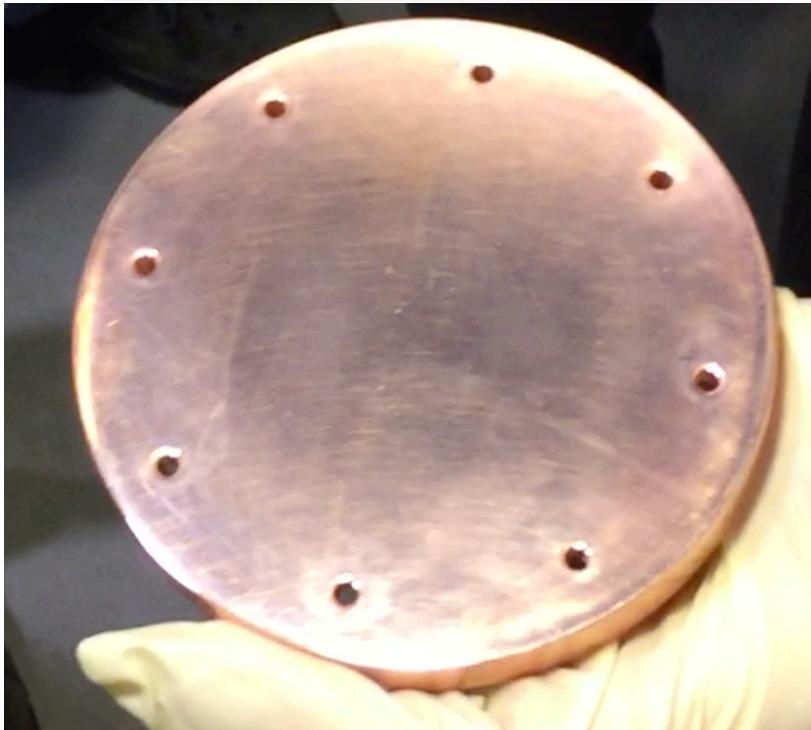
- High brightness (high current, low emittance) electron beam production by photoinjector at SPARC_LAB
- A R&D activity on photocathodes is under development at the SPARC_LAB test facility in order to fully know and characterize each stage of the photocathode “life”
- The n-machining is used to reduce roughness, that is one of contributions to the total beam emittance, and avoid surface contamination caused by other procedures, for example the polishing with diamond paste or the machining with oil

The Machining

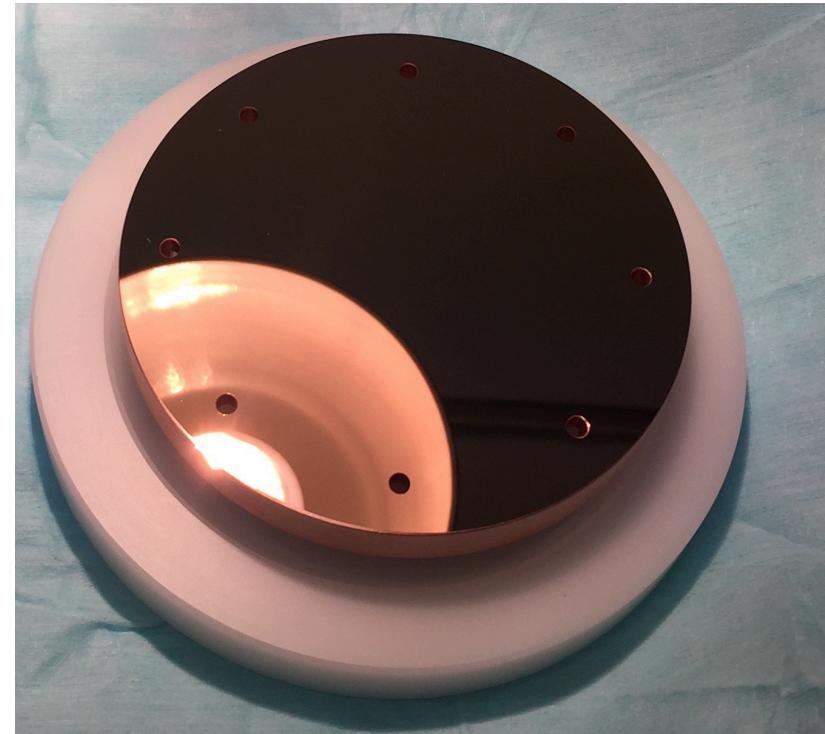
- The photocathode surface has been machined by means of diamond milling and blown with nitrogen. The machining has been done without the use of any oil or cooling fluid (dry machining).

BEFORE MACHINING

Our cathode time life was about 6 years

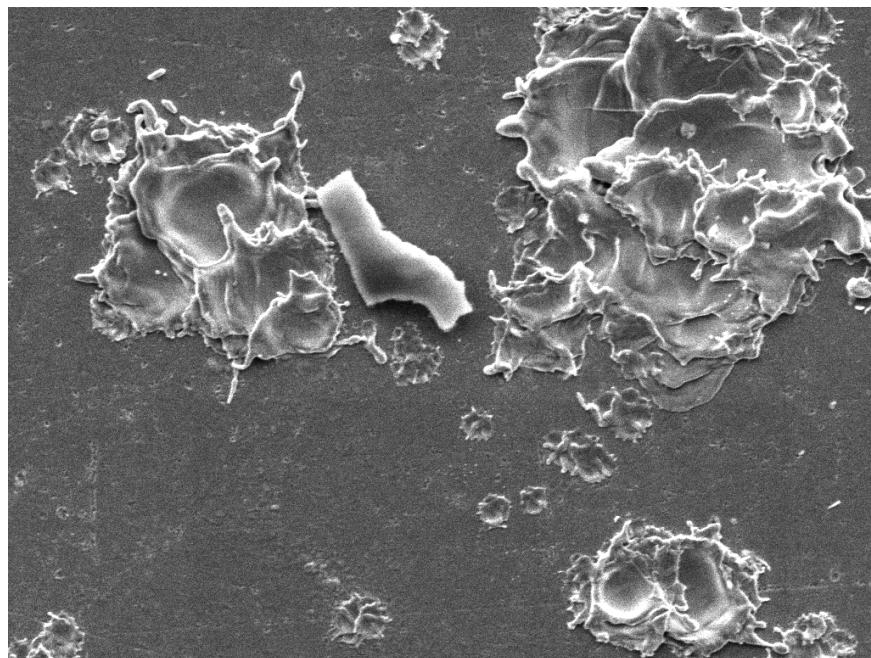


AFTER MACHINING



The Machining

BEFORE MACHINING

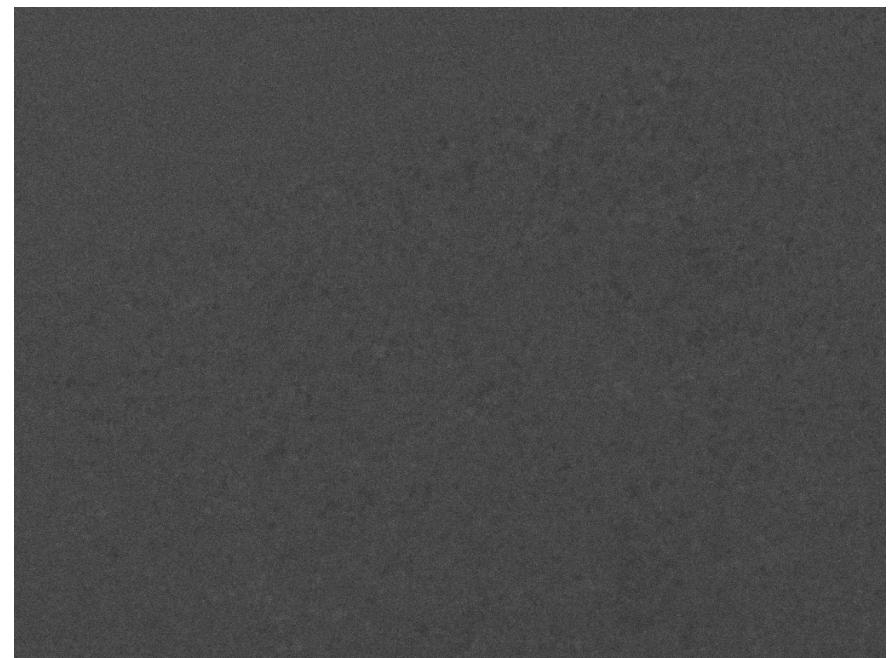


SEM HV: 10.00 kV WD: 39.65 mm
SEM MAG: 2.72 kx Det: SE
Vac: HiVac Date(m/d/y): 01/21/16

VEGA\ TESCAN



AFTER MACHINING

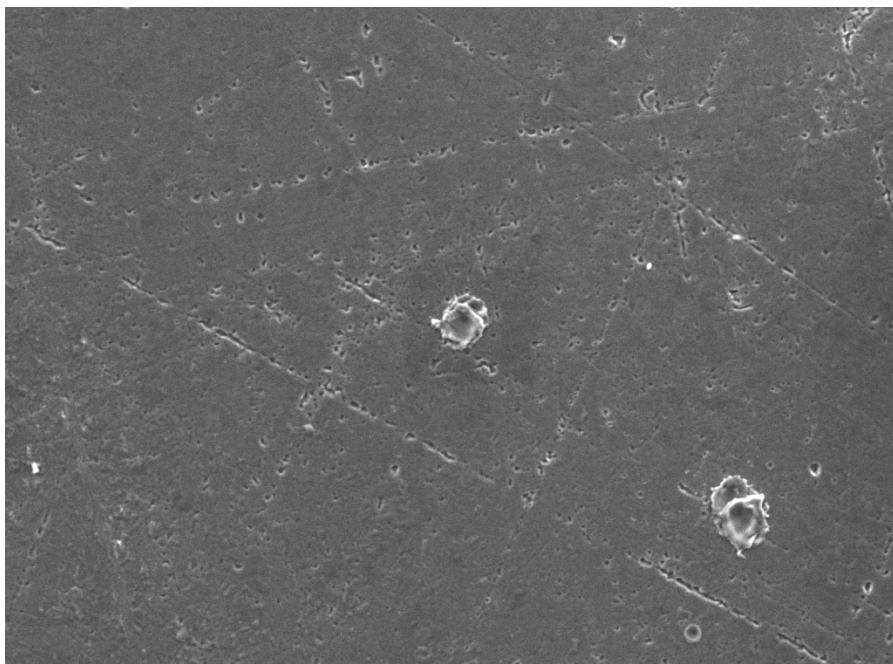


SEM HV: 30.00 kV WD: 15.96 mm
SEM MAG: 2.55 kx Det: SE
Vac: HiVac Date(m/d/y): 05/11/16

VEGA\ TESCAN

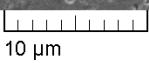


The Machining

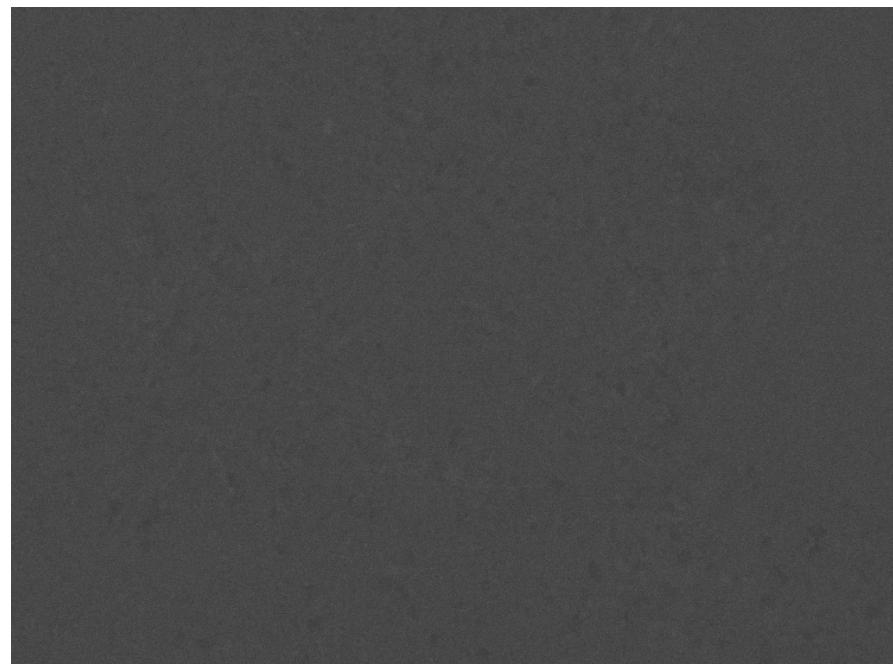
BEFORE MACHINING

SEM HV: 10.00 kV
SEM MAG: 4.07 kx
Vac: HiVac

WD: 39.65 mm
Det: SE
Date(m/d/y): 01/21/16



VEGA\ TESCAN
NEXT - LNF - INFN

AFTER MACHINING

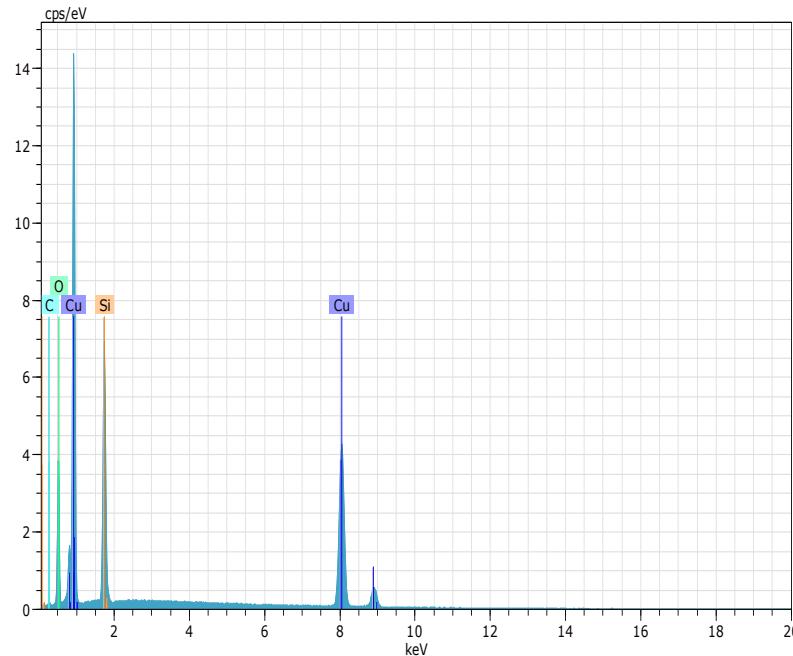
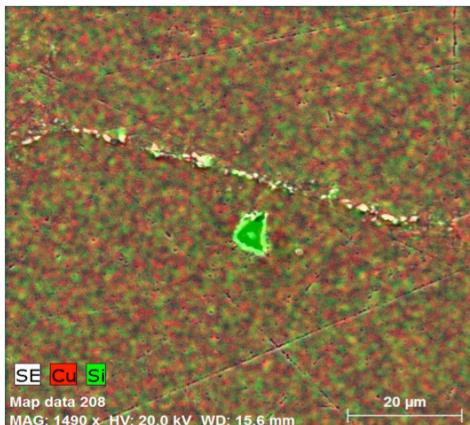
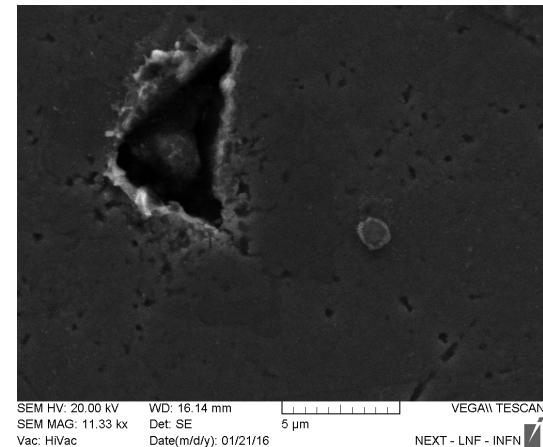
SEM HV: 30.00 kV
SEM MAG: 6.14 kx
Vac: HiVac

WD: 15.91 mm
Det: SE
Date(m/d/y): 05/11/16



VEGA\ TESCAN
NEXT - LNF - INFN

Chemical composition before machining



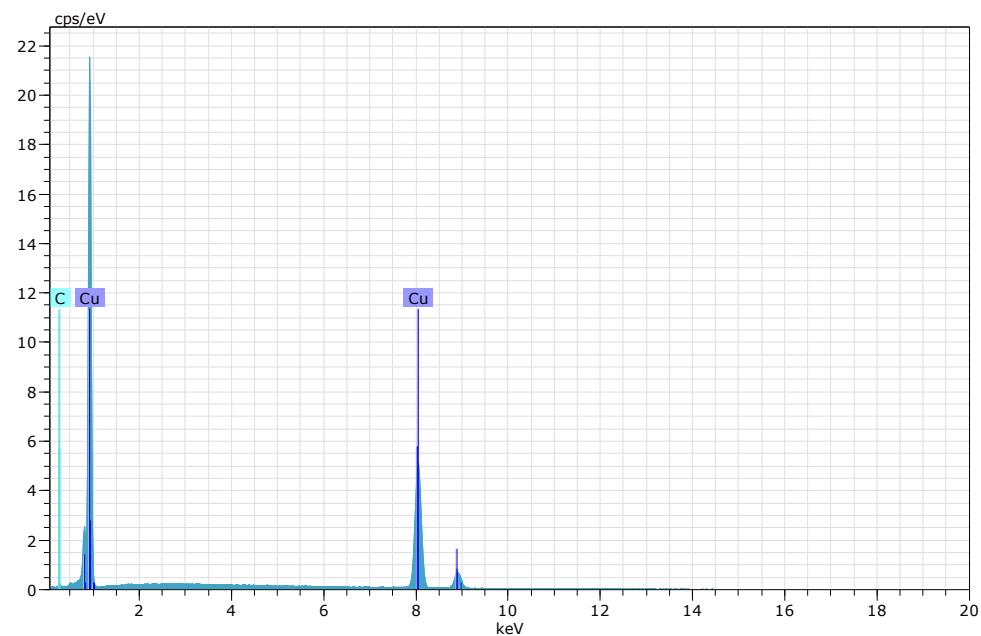
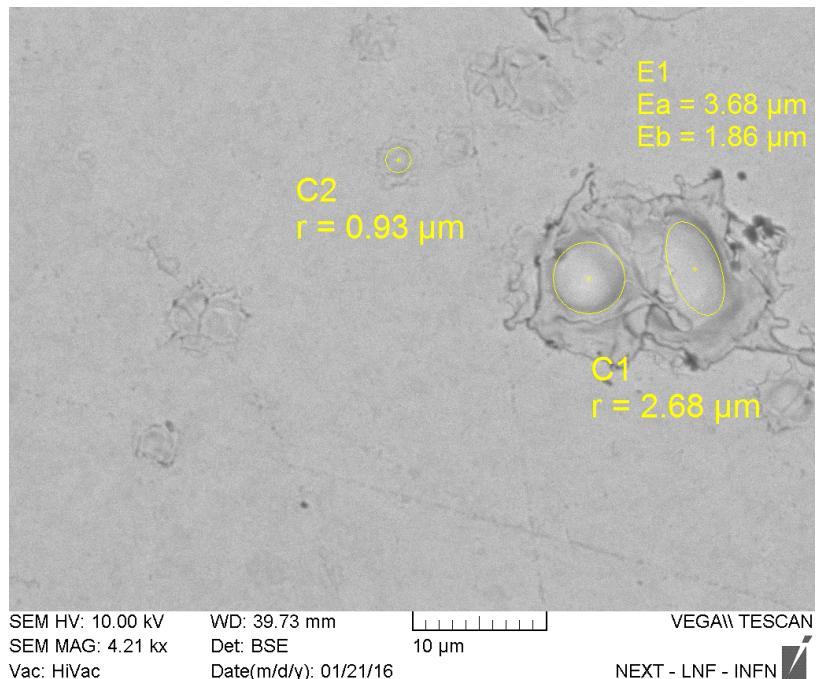
Spectrum: Acquisition 862 - particella.spx

El	AN	Series	unn.	C norm.	C Atom.	C Error (1 Sigma)	K fact.	Z corr.	A corr.	F corr.
			[wt.%]	[wt.%]	[at.%]		[wt.%]			

Cu	29	K-series	62.20	63.79	34.62	1.72	0.548	1.114	1.000	1.044
O	8	K-series	17.08	17.51	37.76	2.31	0.377	0.464	1.000	1.000
Si	14	K-series	15.46	15.86	19.47	0.69	0.131	1.203	1.000	1.004
C	6	K-series	2.77	2.84	8.15	0.76	0.077	0.369	1.000	1.000

Total: 97.51 100.00 100.00

Chemical composition before machining



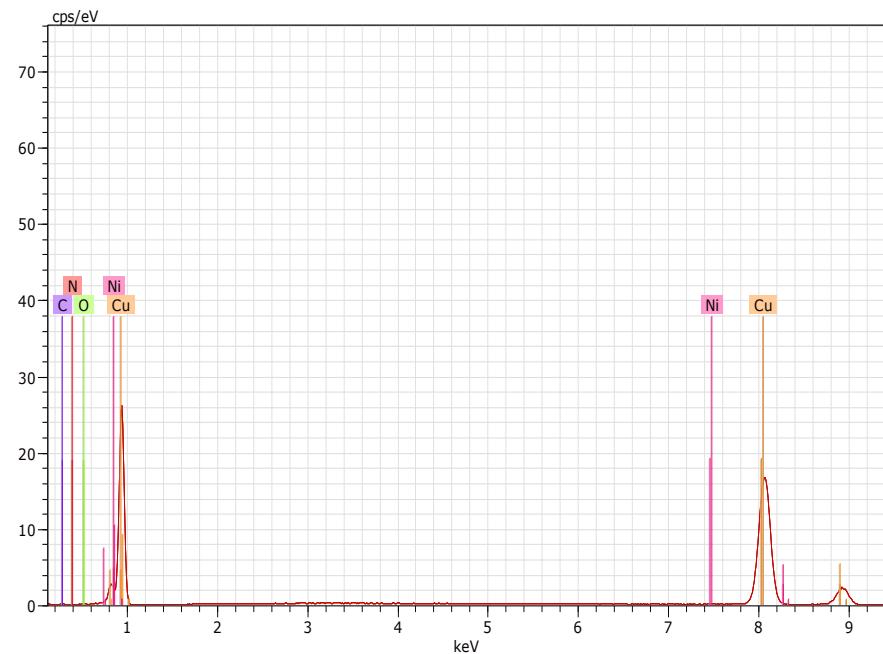
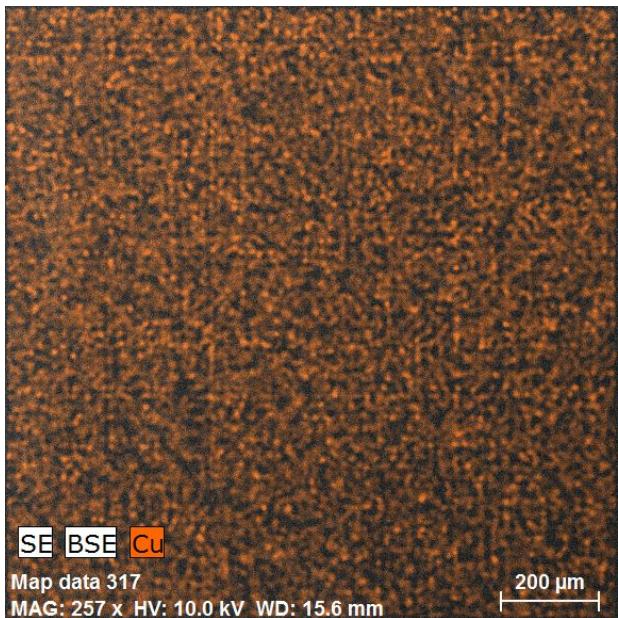
Spectrum: Acquisition 861-Generale.spx

El AN Series	unn. C norm. C	Atom. C	Error (1 Sigma)	K fact.	Z corr.	A corr.	F corr.
[wt.%]	[wt.%]	[at.%]		[wt.%]			

Cu 29 K-series	88.20	96.47	83.80	2.42	0.862	1.078	1.000	1.039
C 6 K-series	3.22	3.53	16.20	0.86	0.091	0.387	1.000	1.000

Total: 91.43 100.00 100.00

Chemical composition after machining

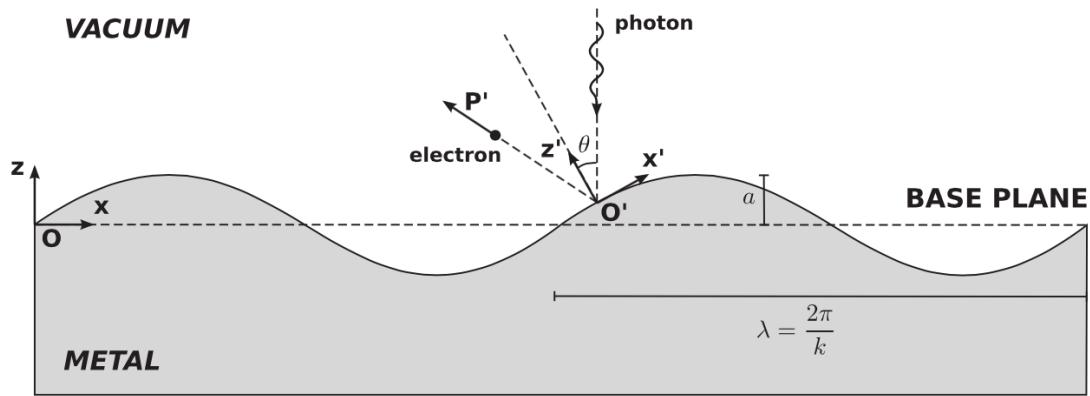


Spectrum: Acquisition 877

E1	AN	Series	Net	unn.	C	norm.	C	Atom.	C	Error	(1 Sigma)
			[wt.%]		[wt.%]		[at.%]				[wt.%]
<hr/>											
Cu	29	L-series	289089	98.81	98.81	95.69			10.64		
C	6	K-series	1280	0.47	0.47	2.39			0.12		
Ni	28	L-series	1453	0.34	0.34	0.35			0.09		
O	8	K-series	1150	0.22	0.22	0.86			0.07		
N	7	K-series	466	0.16	0.16	0.71			0.07		
<hr/>											
Total: 100.00 100.00 100.00											

Surface roughness induced emittance

- **Surface roughness** on cathode introduces a transverse electric field that increases the transverse momentum, causing **emittance growth**.

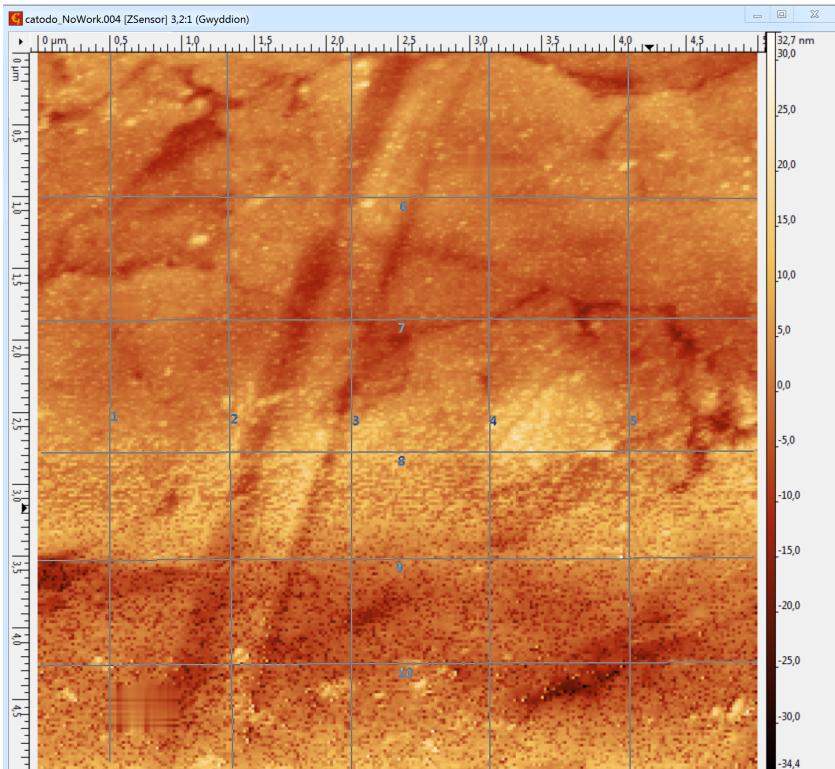


- $z=a \cos ((2\pi/\lambda)x)$, surface morphology function
- a , amplitude of the uneven surface
- λ , period of fluctuation

$$\varepsilon_{ns} = \sigma_x \sqrt{\frac{e\pi^2 a^2 E_{rf} \sin \vartheta_{rf}}{2m_0 c^2 \lambda}}$$

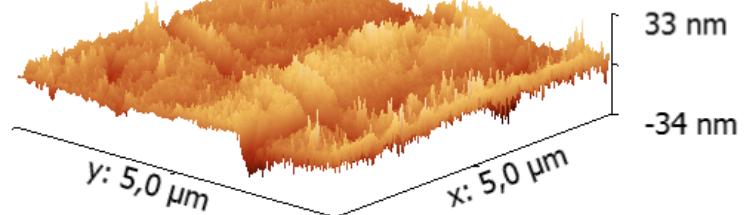
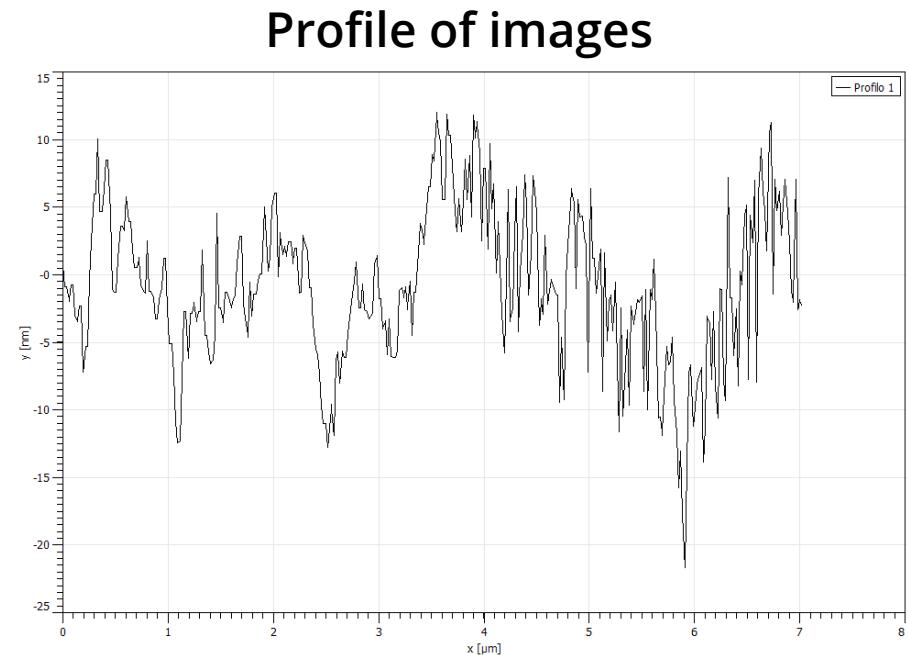
Z. Zhang and C. Tang, *Analytical study on emittance growth caused by roughness of a metallic photocathode*, PRST-AB 18, 053401 (2015)

D. Xiang et al., *First principle measurements of thermal emittance for copper and magnesium*, Proc. of PAC07, Albuquerque, New Mexico, USA



Statistical parameters:

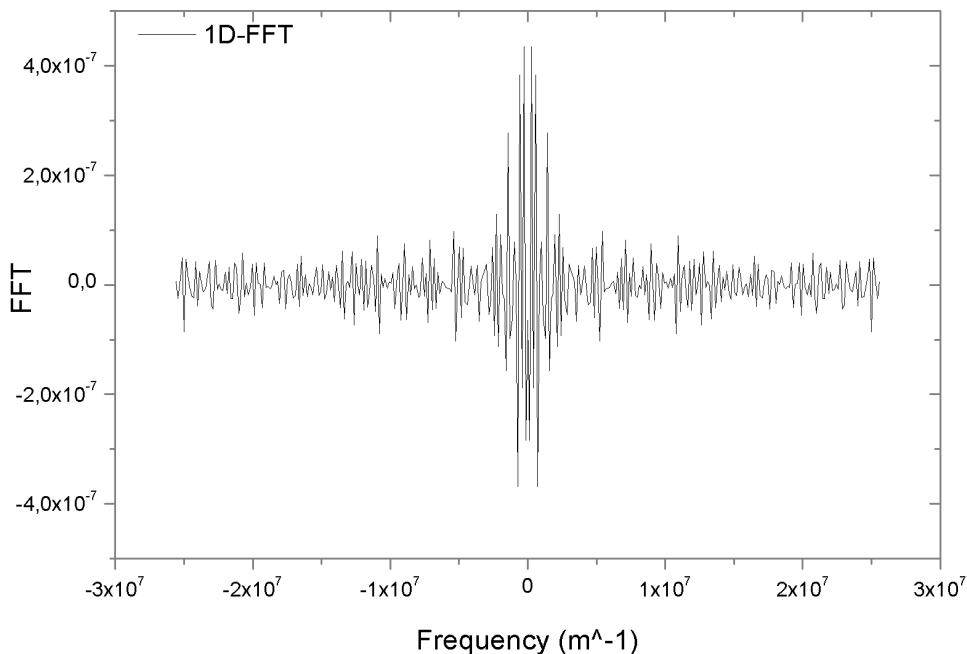
Min_value: -34,4 nm
Max_value: 32,6 nm
Ra (Sa): 4,3 nm
Rms (Sq): 5,7 nm



Fourier transform of AFM image

$$\operatorname{Re} \{F[l]\} = \frac{1}{N} \sum_{n=0}^{N-1} \operatorname{Re} \{f[n]\} \cos 2\pi \frac{n}{N} l$$

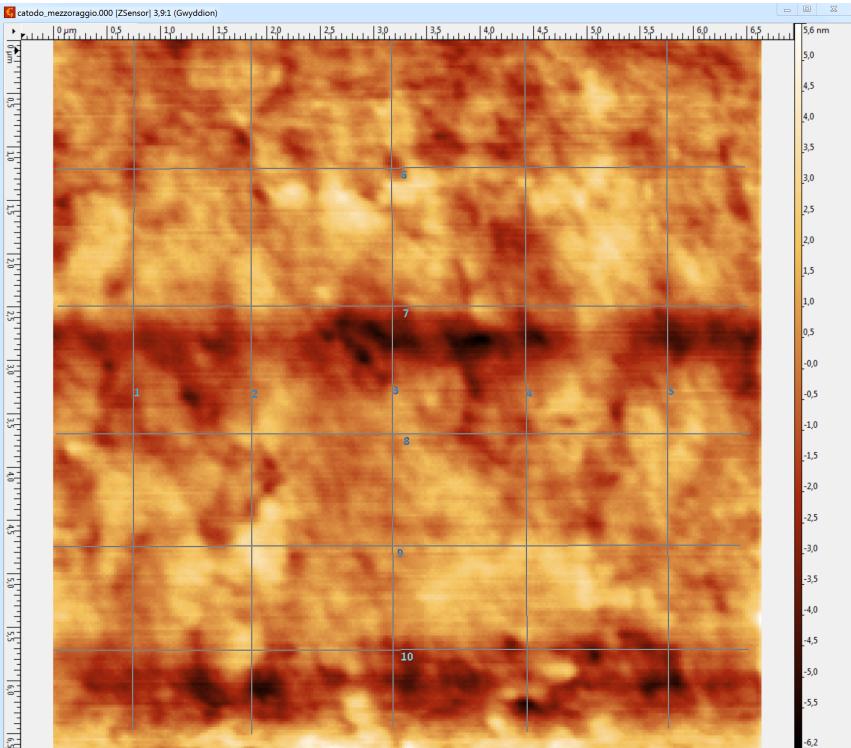
1D-DFT



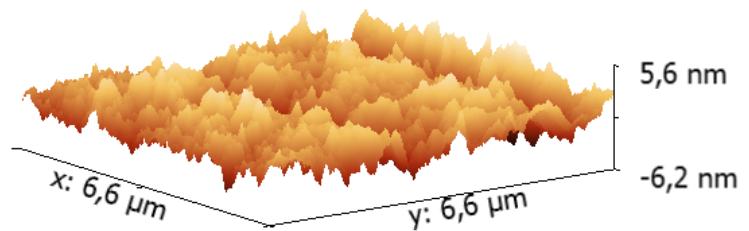
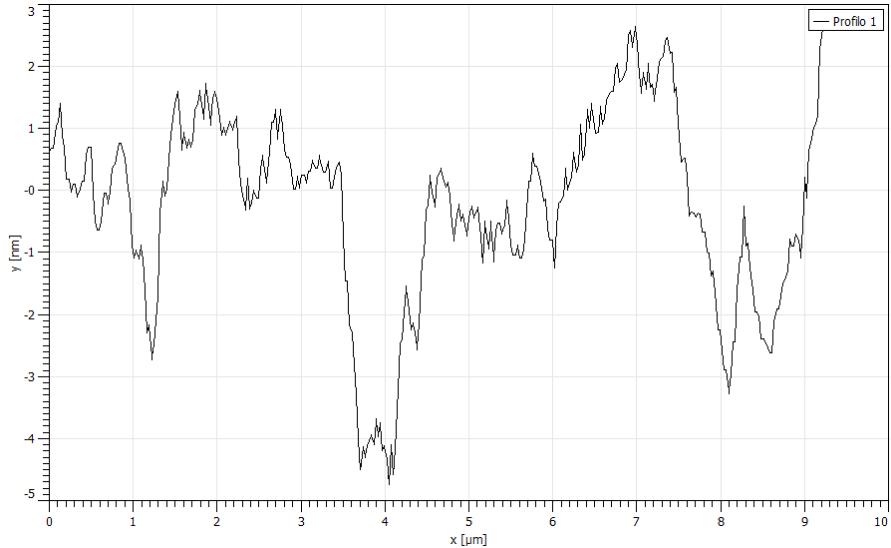
$$\left[\begin{array}{l} a_n = \operatorname{Re} \{f[n]\} \\ \lambda_n = \frac{L_{cathode}}{n} \end{array} \right]$$

$$\sum_{n=0}^{N-1} \frac{a_n^2}{\lambda_n} = \underline{3.13e-11m}$$

AFM analysis after n-machining



Profile of images



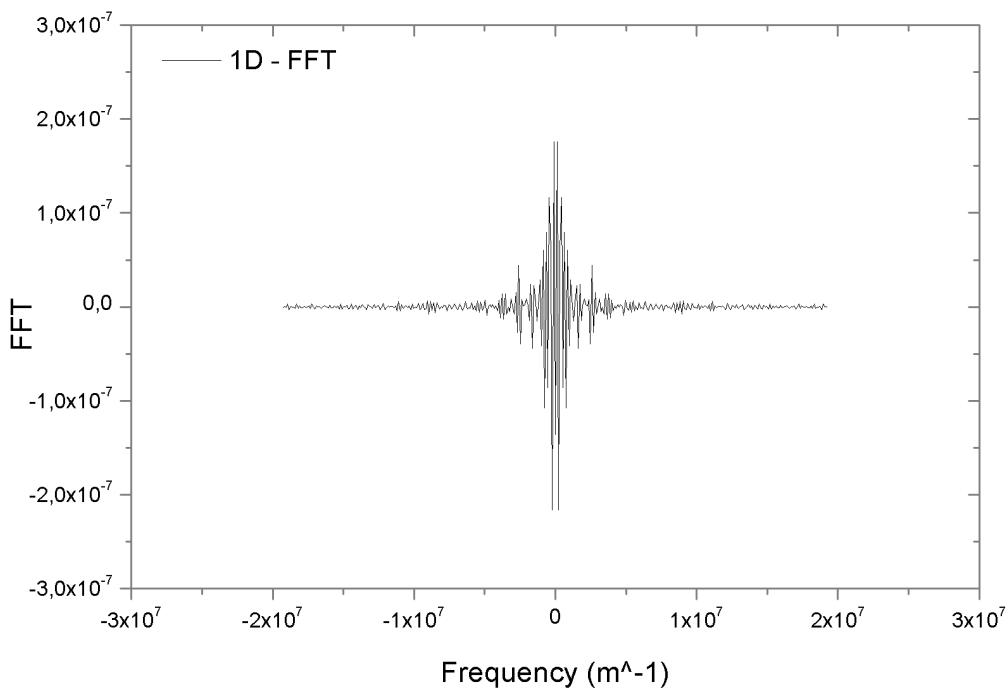
Statistical parameters:

Min_value: -6,16 nm
Max_value: 5,60 nm
Ra (Sa): 1,18 nm
Rms (Sq): 1,501 nm

Fourier transform of AFM image

$$\operatorname{Re} \{F[l]\} = \frac{1}{N} \sum_{n=0}^{N-1} \operatorname{Re} \{f[n]\} \cos 2\pi \frac{n}{N} l$$

1D-DFT



$$\left[\begin{array}{l} a_n = \operatorname{Re} \{f[n]\} \\ \lambda_n = \frac{L_{cathode}}{n} \end{array} \right]$$

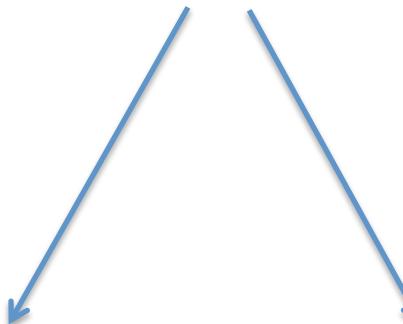
$$\sum_{n=0}^{N-1} \frac{a_n^2}{\lambda_n} = 4e - 13m$$

$$\epsilon_{total}^2 = \sum_{n=0}^{N-1} \epsilon^2(a_n, k_n) = \sigma_x^2 \frac{\pi^2 e E_{rf} \sin \theta_{rf}}{2mc^2} \sum_{n=0}^{N-1} \frac{a_n^2}{\lambda_n}$$

$$E_{rf} = 97 \text{ MV/m}$$

$$\vartheta_{rf} = 30^\circ$$

$$\sigma_x = 0.3 \text{ mm}$$



Before n-machining

$$\sum_{n=0}^{N-1} \frac{a_n^2}{\lambda_n} = 3.13e - 11m$$

$$\sqrt{\epsilon_{total}^2} = 0.04 \mu m$$

After n-machining

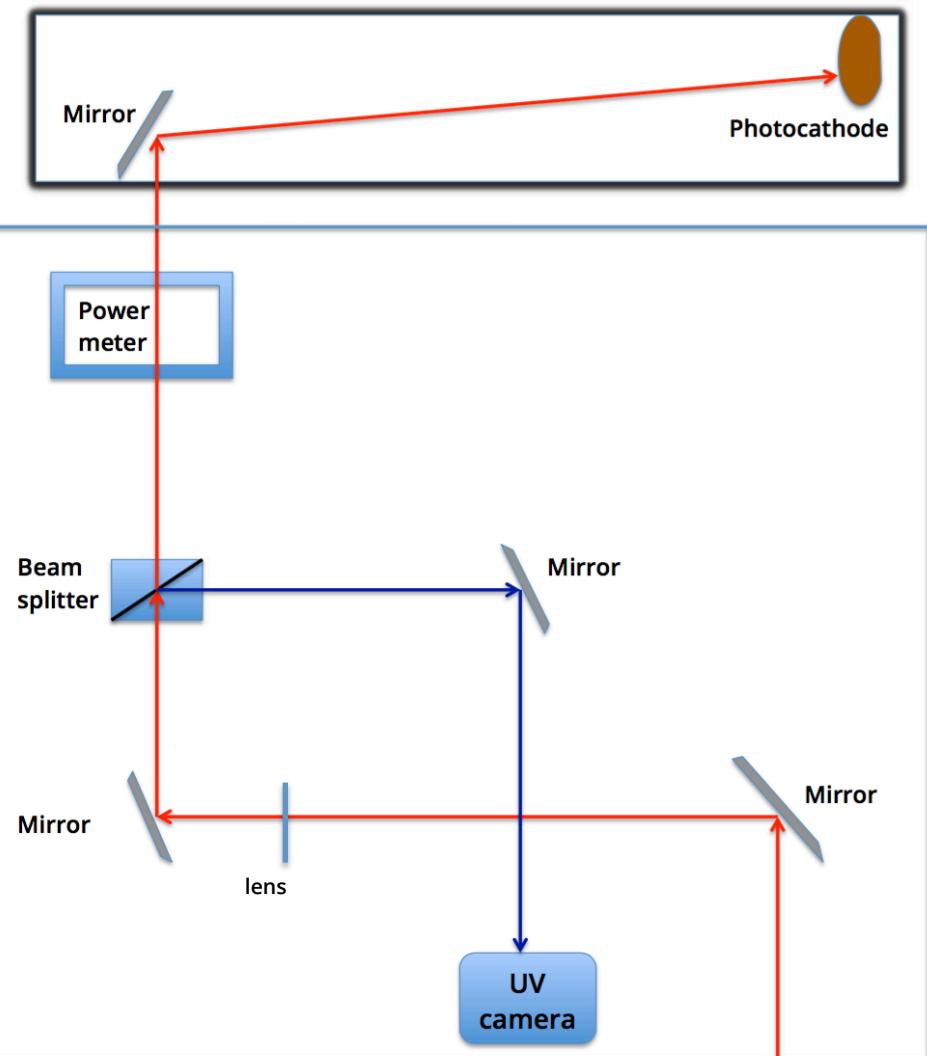
$$\sum_{n=0}^{N-1} \frac{a_n^2}{\lambda_n} = 4e - 13m$$

$$\sqrt{\epsilon_{total}^2} = 0.004 \mu m$$

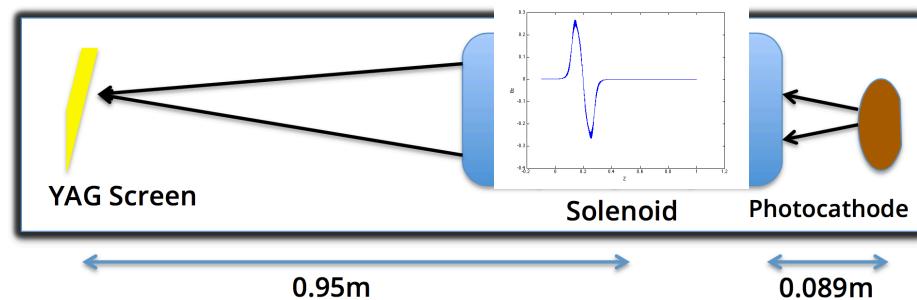
Emittance measurements: experimental set up

- Photocathode laser

Beam line



- Beam line



Solenoid is in not-rotating configuration, that is no x/y coupling

Emittance measurements: measurements method

Solenoid Scan Technique:

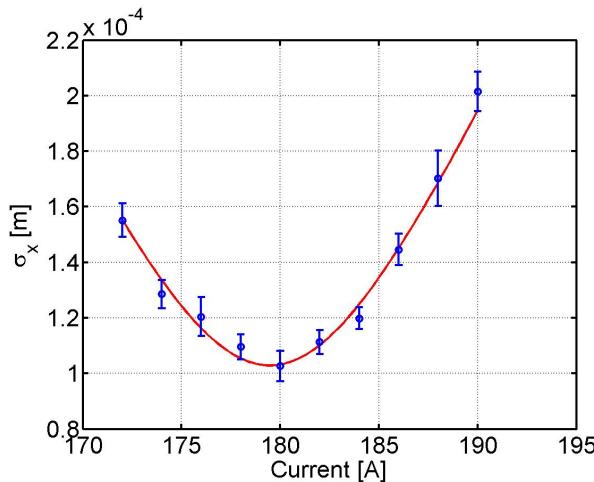
- Measure of beam size squared on YAG Screen for different solenoid field is given by:

$$\langle x_i \rangle^2 = R_{11}^{(i)2} \langle x_0^2 \rangle + 2R_{11}^{(i)}R_{12}^{(i)} \langle x_0 x_0' \rangle + R_{12}^{(i)2} \langle x_0'^2 \rangle$$

Where the coefficients R_{11} and R_{12} are the elements of beam line transfer matrix.

- Total normalized emittance has been computed at the entrance of gun solenoid:

$$\varepsilon_{nx,rms} = \gamma \beta \sqrt{\langle x_0^2 \rangle \langle x_0'^2 \rangle - \langle x_0 x_0' \rangle^2}$$



At the entrance of gun solenoid:

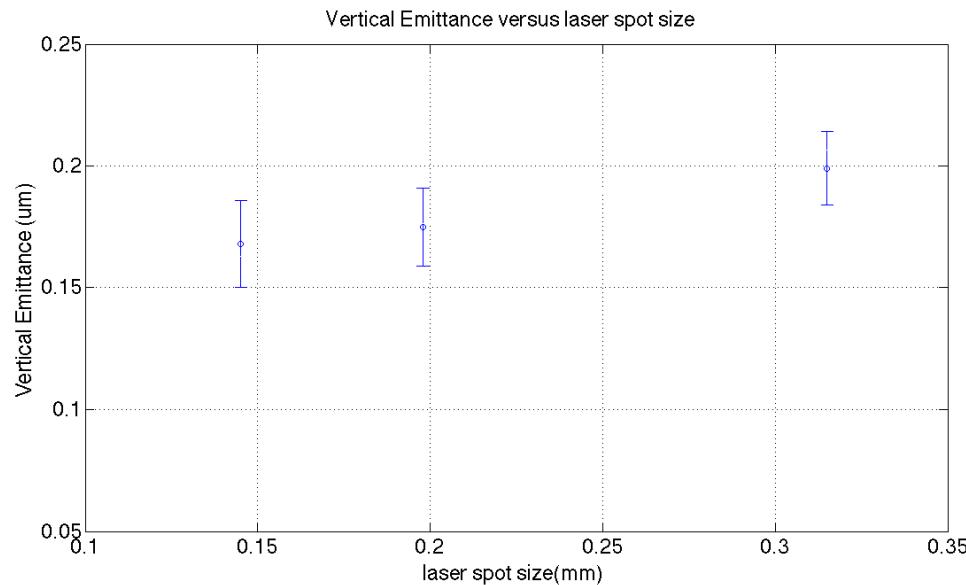
$$\varepsilon_{nx} = 0.16 \pm 0.01 mmmrad$$

$$\beta x_in = 0.38 \pm 0.04 m$$

$$\alpha x_in = -6.8 \pm 0.8$$

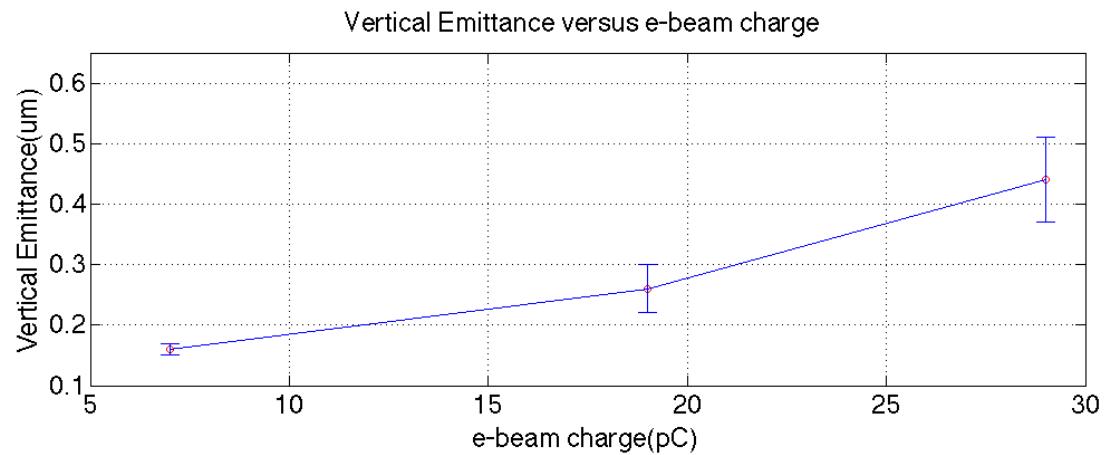
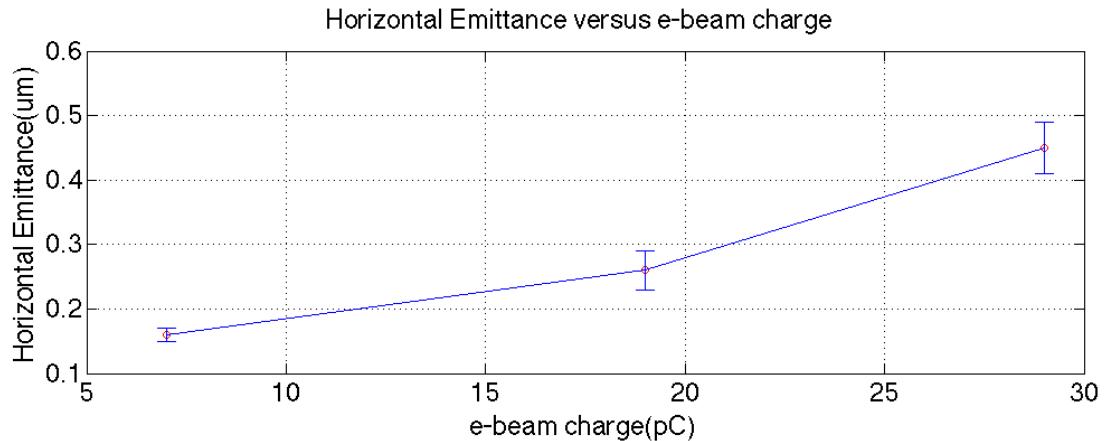
Parameters:

- $E_{peak} = 84\text{MV/m}$
- Working RF phase= 30°
- Laser pulse length=5ps - FWHM (Gaussian profile)
- $E = 4.01 \pm 0.05\text{MeV}$ - Energy at the gun exit
- Bunch charge $\approx 6\text{pC}$



Parameters:

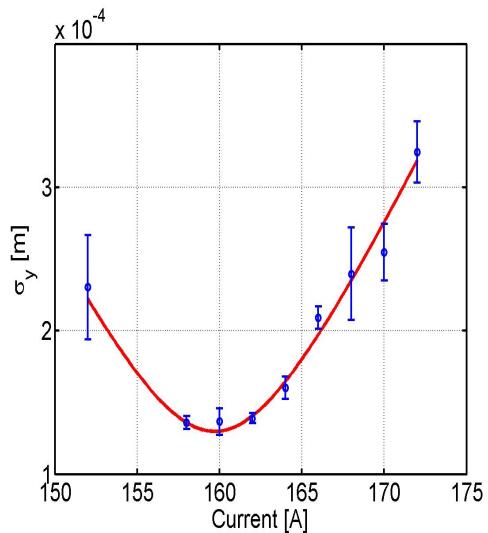
- $E_{peak} = 97\text{MV/m}$
- Working RF phase = 30°
- Laser pulse length = 5ps
- FWHM (Gaussian profile)
- $E = 4.53 \pm 0.05\text{MeV}$ - Energy at the gun exit
- $\sigma_{x,y,\text{rms}}$ (Laser spot) $\approx 0.3\text{mm}$ (Flat top profile)



Before n-machining

Parameters:

- $E_{peak} = 84\text{MV/m}$
- Working RF phase = 30°
- Laser pulse length = 5ps - FWHM (Gaussian profile)
- $E = 4.01 \pm 0.05\text{MeV}$ - Energy at the gun exit
- Bunch charge $\approx 6\text{pC}$



At the entrance of gun solenoid:

$$\varepsilon_{nx} = 0.28 \pm 0.04\text{mm mrad}$$

$$\beta x_{in} = 0.42 \pm 0.06\text{m}$$

$$\alpha x_{in} = -7.33 \pm 0.13$$

Emittance measurements before and after n-machining

Parameters:

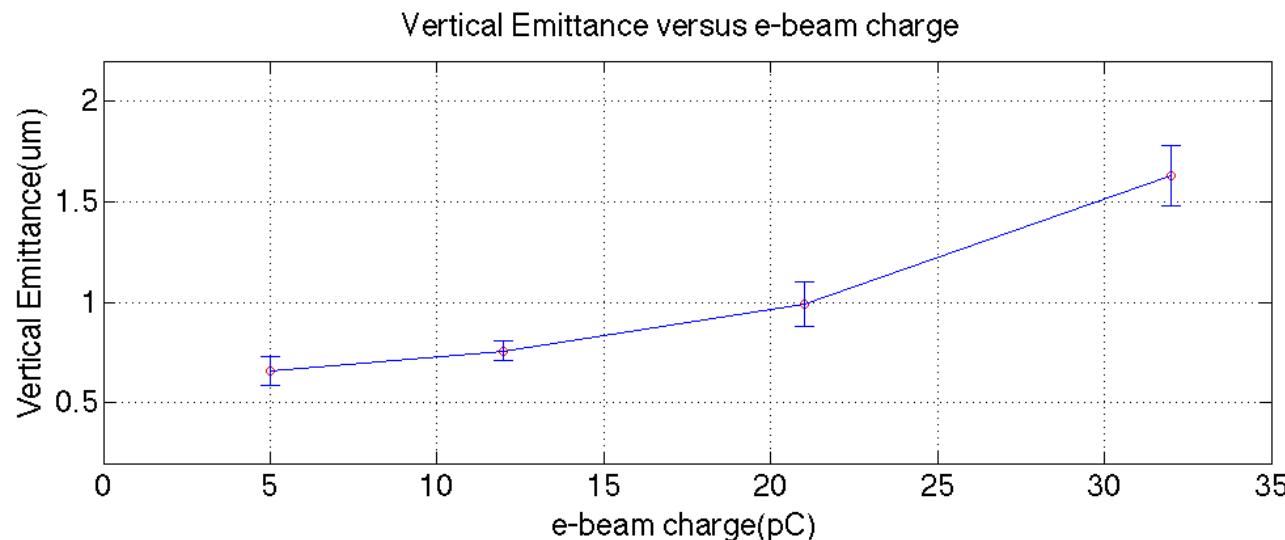
- Epeak= 84MV/m
- Working RF phase=30°
- Laser pulse length =5ps - FWHM (Gaussian profile)
- Bunch charge≈ 6pC

	<i>Before n-machining</i>		<i>After n-machining</i>	
E_acc (MV/m)	ϵ_x (mm mrad)	ϵ_y (mm mrad)	ϵ_x (mm mrad)	ϵ_y (mm mrad)
84	0.24±0.04	0.28±0.04	0.105±0.012	0.114±0.010

Yttrium preliminary results: total beam emittance measurements

Parameters:

- $E_{peak} = 110\text{MV/m}$
- Working RF phase = 30°
- Laser pulse length = 5.3ps - FWHM (Gaussian profile)
- $E = 4.66\text{MeV}$ - Energy at the gun exit
- $\sigma_{x,y,\text{rms}}$ (Laser spot) $\approx 0.11\text{mm}$ (Gaussian profile)



Conclusions

- For our applications the **dry machining** is a good procedure because we don't have residual of diamond paste or oil
- We obtain an excellent roughness ($\leq 2\text{nm}$) typical of monocrystalline copper cathode
- With the n-machining we improved of a factor **2** the total beam emittance
- **Future work:** intrinsic emittance computation for Copper and Yttrium photocathodes, HomDyn / GPT simulations for the theoretical comparison and QE measurements

Thanks to

- ❖ D. Alesini, M.P. Anania, M. Bellaveglia, S. Bellucci, A. Biagioni, F. Bisesto, F. Cardelli, E. Chiadroni, G. Costa, D. Di Giovenale, G. Di Pirro, R. Di Raddo, A. Giribono, M. Ferrario, F. Micciulla, R. Pompili, L. Piersanti, V. Shpakov, A. Stella, F. Villa (INFN-LNF)
- ❖ A. Cianchi (INFN-Roma To Vergata and Università di Roma "Tor Vergata")
- ❖ Andrea Mostacci, Daniele Passeri (SBAI- Università di Roma "La Sapienza")
- ❖ A. Lorusso (Università del Salento, Dipartimento di Matematica e Fisica "E. De Giorgi", INFN-Sezione di Lecce)
- ❖ Mauro Trovò (Elettra - Sincrotrone Trieste SCpA)



Finally it's over



Thank you for your attention